



Receipt  
#8/B  
PATENT  
5298-02502/PM980196  
OCT 18 2002  
TECHNOLOGY CENTER 2800  
RECEIVED

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:  
Sethuraman et al.

Serial No. 09/779,123

Filed: February 07, 2001

For: A PLANARIZED SEMICONDUCTOR  
INTERCONNECT TOPOGRAPHY  
AND METHOD FOR POLISHING A  
METAL LAYER TO FORM  
INTERCONNECT

Group Art Unit: 2823

Examiner: Lee, H.

Atty. Dkt. No. 5298-02502

I hereby certify that this correspondence is being deposited  
with the U.S. Postal Service with sufficient postage as First Class  
Mail in an envelope addressed to: **Box: Non-Fee Amendment,**  
Commissioner for Patents, Washington, D.C. 20231, on the date  
indicated below:

October 3, 2002

Date

Kevin L. Daffer

**AMENDMENT; RESPONSE TO OFFICE ACTION MAILED JULY 3, 2002**

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir/ Madam:

This paper is submitted in response to the Office Action mailed July 3, 2002 to further highlight reasons why the application is in condition for allowance.

Please amend the case as follows:

**In the Claims:**

Please replace claims 1-3, 10-11, and 17 with the amended claims below. A "marked-up" version of each amendment is included in **Attachment A**.